



Serial No. 10/630,773
Supplemental Amendment Dated: October 5, 2006
Reply to Office Action Mailed: March 26, 2006
Attorney Docket No. 056208.52613US

Amendments to the Specification:

Please replace paragraph [0052] with the following amended paragraph:

[0052] When the probing portion is to be installed on the hybrid IC substrate 9, it is effective to form an opening 22 in the [[by]] overcoating glass or resin 28 as shown in Figure 5, and to coat the opening with a conductive metal such as solder or metallic paste 27. However, in this case, when the wettability of solder or metallic paste to the conductor wires is poor, the conductor wires at the ends, particularly in the corners are exposed and may be corroded by corrosive gas.